



Features



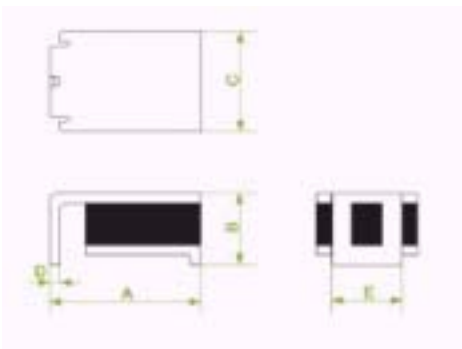
- Surface mount devices
- High voltage surge capabilities
- Available in lead-free version
- Agency Recognition: UL、CSA、TUV



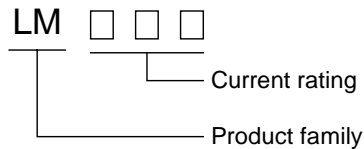
LM series Surface mount devices

Product Dimensions(mm)

Part number	A	B	C	D	E
	Max	Max	Max	Min	Typ
LM080	9.4	3.4	7.4	0.3	3.8
LM130	9.4	3.4	7.4	0.3	3.8



■ Marking system



* Lead-free devices are available, the right logo is lead-free mark of wayon.



Electrical Characteristics

Part number	I_H (A)	I_T (A)	Current(A)	T_{trip} Time(S)	V_{max} interrupt (V)	I_{max} (A)	Pd_{typ} (W)	R_{min} ()	R_{max} ()
LM080	0.080	0.160	1.00	0.45	250	3.0	1.00	14.0	22.0
LM130	0.130	0.260	1.00	0.90	250	3.0	3.00	6.5	12.0

I_H =Hold current: maximum current at which the device will not trip at 25 still air.

I_T =Trip current: minimum current at which the device will always trip at 25 still air.

V_{max} =Maximum voltage device can withstand without damage at rated current.

I_{max} =Maximum fault current device can withstand without damage at rated voltage.

T_{trip} =Maximum time to trip(s) at assigned current.

Pd_{typ} =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min} =Minimum device resistance at 25 prior to tripping.

R_{max} =Maximum device resistance at 25 prior to tripping.

Thermal Derating Chart- I_H (A)

Part number	Maximum ambient operating temperatures()								
	-40	-20	0	25	40	50	60	70	85
LM080	0.124	0.110	0.095	0.080	0.066	0.059	0.051	0.044	0.033
LM130	0.208	0.182	0.156	0.130	0.104	0.091	0.078	0.065	0.045

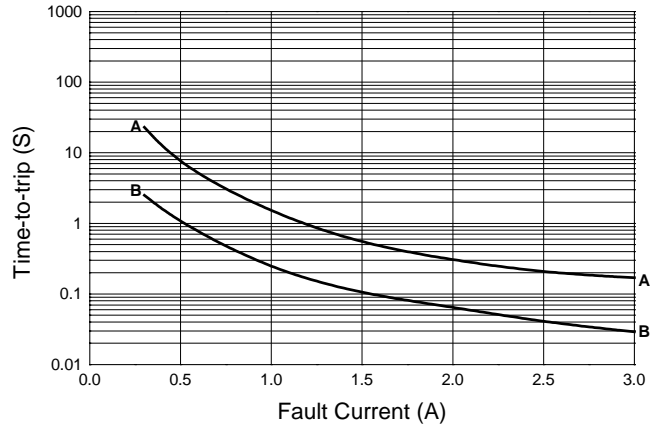
Test Procedures And Requirements

Test	Test Conditions	Accept/Reject Criteria
Resistance	In still air @ 25	R_{min} R R_{max}
Time to Trip	Specified current, V_{max} , 25	T maximum Time to Trip
Hold Current	60min, at I_H	No trip
Trip Cycle Life	V_{max} , I_{max} , 20cycles	No arcing or burning
Trip Endurance	V_{max} , 15min	No arcing or burning

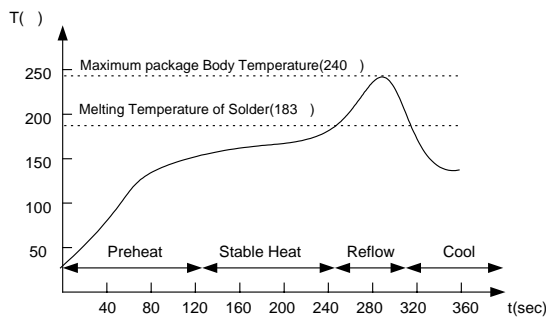
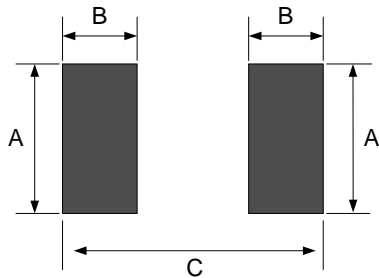
Typical Time-to-Trip Charts at 25

A=LM130

B=LM080



Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LM080	4.6	1.8	6.1
LM130	4.6	1.8	6.1

* Recommended reflow methods: IR, Vapor phase oven, hot air oven.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Bulk:

LM080~LM130..... 1000pcs per bag

Tape & Reel:

LM080~LM130.....1000pcs per reel